

PEREGRINE MATERIAL DECLARATION FORM

Product:	PE42553
Ordering Codes:	PE42553B-Z
Description:	UltraCMOS® SPDT RF Switch 9 kHz - 8 GHz
Package:	16L 3x3 QFN
Environmental Compliance	EU RoHS2 Directive 2011/65/EC, REACH - EU ECHA SVHC, Arsenic Free, JIG 101 - EIA/EICTA/JEITA, Halogen Free - IEC61249-2-21, PFOS Free - 2006/122/EC, Antimony Trioxide Free
Lead Finish	NiPdAu
Availability	Now

Component	Material	CAS Number	Weight (mg)	%	PPM
SOI Wafer	Aluminum oxide	1344-28-1	1.244301	5.37%	53,715.10
SOI Wafer	Aluminum	7429-90-5	0.003785	0.02%	163.39
SOI Wafer	Silicon	7440-21-3	0.000252	0.00%	10.89
SOI Wafer	Arsenic	7440-38-2	0.000001	0.00%	0.05
SOI Wafer	Boron	7440-42-8	0.000001	0.00%	0.05
SOI Wafer	Phosphorus	7723-14-0	0.000005	0.00%	0.22
SOI Wafer	Titanium	7440-32-6	0.000631	0.00%	27.23
SOI Wafer	Tungsten	7440-33-7	0.012616	0.05%	544.63
SOI Wafer	Cobalt	7440-48-4	0.000025	0.00%	1.09
SOI Wafer	Copper	7440-50-8	0.000010	0.00%	0.44
Leadframe	Copper	7440-50-8	9.054500	39.09%	390,872.75
Leadframe	Chromium	7440-47-3	0.022800	0.10%	984.25
Leadframe	Tin	7440-31-5	0.022800	0.10%	984.25
Leadframe	Zinc	7440-66-6	0.020100	0.09%	867.69
Die Attach	Silver	7440-22-4	0.135200	0.58%	5,836.43
Die Attach	2-Butoxyethyl Acetate	112-07-2	0.015200	0.07%	656.17
Die Attach	2-Propenoic acid, 3-(trimethoxysilyl)propy	4369-14-6	0.001500	0.01%	64.75
Wire	Gold	7440-57-5	0.160600	0.69%	6,932.92
Plating	Nickel	7440-02-0	0.066600	0.29%	2,875.05
Plating	Palladium	7440-05-3	0.005400	0.02%	233.11
Plating	Gold	7440-57-5	0.000200	0.00%	8.63
Mold Compound	Silica Fused	60676-86-0	11.369300	49.08%	490,800.10
Mold Compound	Epoxy Resin	Trade secret	0.495900	2.14%	21,407.45
Mold Compound	Phenol Resin	Trade secret	0.495900	2.14%	21,407.45
Mold Compound	Carbon Black	1333-86-4	0.037200	0.16%	1,605.88
Total Weight (mg)			23.164828	100.00%	1,000,000